TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (MACH II π -MOS V)

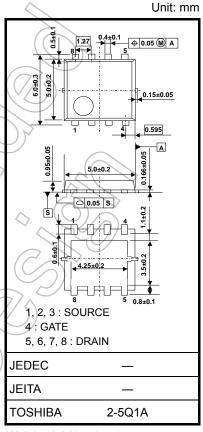
TPCA8008-H

High Speed Switching Applications Switching Regulator Applications DC/DC Converter Applications

- Small footprint due to a small and thin package
- High-speed switching
- Small gate charge: QSW = 3.7 nC (typ.)
- Low drain-source ON-resistance: RDS (ON) = 0.47Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 3.3S$ (typ.)
- Low leakage current: $I_{DSS} = 100 \mu A (max) (V_{DS} = 250 V)$
- Enhancement mode: $V_{th} = 2.0 \text{ to } 4.0 \text{ V (VDS} = 10 \text{ V, ID} = 1 \text{ mA})$

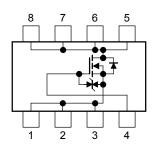
Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	250	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V _{DGR}	250	V
Gate-source voltage		V _{GSS}	±20	<u> </u>
Drain current	DC (Note 1)	ID	4	^
	Pulsed (Note 1)	IDP	8	Α `
Drain power dissipation (Tc=25°C)		(PD \	45	w
Drain power dissipation	on (t = 10 s) (Note 2a)	PD	2.8	W
Drain power dissipation (t = 10 s) (Note 2b)		PD	1,6	W
Single-pulse avalanche energy (Note 3)		EAS	11	mJ
Avalanche current		I _{AR}	4	Α
Repetitive avalanche energy (Tc=25°C) (Note 4)		EAR	4.5	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55 to 150	°C



Weight: 0.069 g (typ.)

Circuit Configuration



Note: For Notes 1 to 4, refer to the next page.

Using continuously under heavy loads (e.g. the application of high

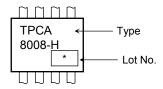
temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case (Tc=25°C)	R _{th (ch-c)}	2.78	°C/W
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2a)	R _{th (ch-a)}	44.6	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	78.1	°C/W

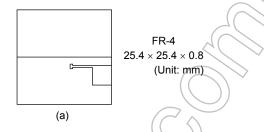
Marking (Note 5)

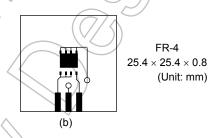


Note 1: The channel temperature should not exceed 150°C during use.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)

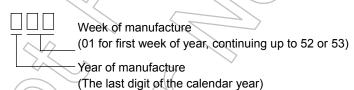




Note 3: $V_{DD} = 50 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 1mH, $R_G = 25 \Omega$, $I_{AR} = 4 \text{ A}$

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: * Weekly code: (Three digits)



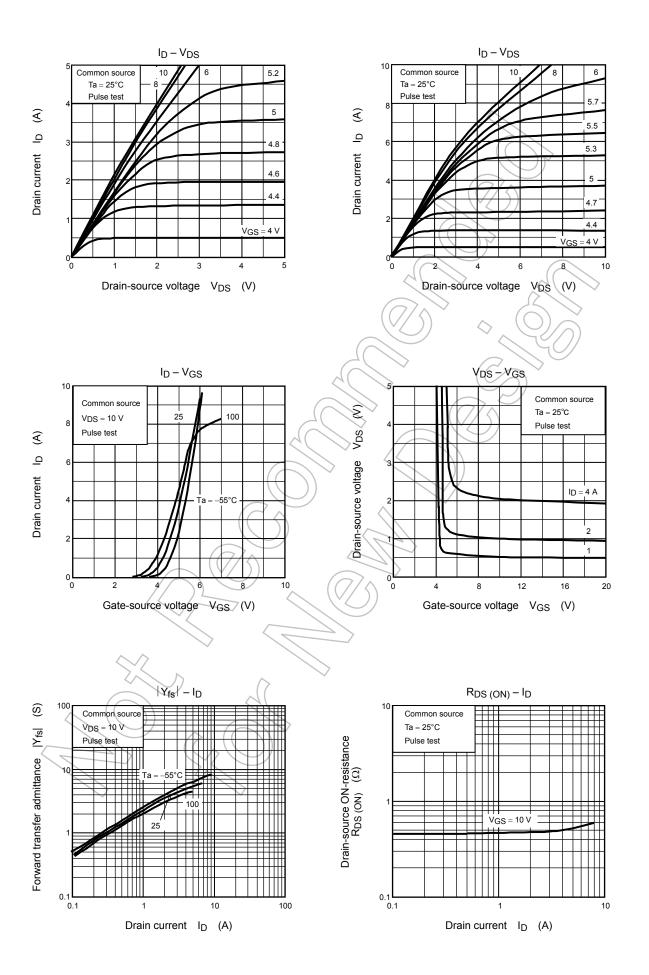
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Electrical Characteristics (Ta = 25°C)

Cha	aracteristic	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage curi	rent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ	
Drain cutoff curre	nt	I _{DSS}	V _{DS} = 250 V, V _{GS} = 0 V	_	_	100	μΑ	
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	250	_			
		V _(BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -5 \text{ V}$	250	_		V	
			$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	200))^_	_		
Gate threshold vo	Itage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V	
Drain-source ON-	resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 2 A	\bigcirc	0.47	0.58	Ω	
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2 A	1.5	3.3	_	S	
Input capacitance		C _{iss}		_	600	_		
Reverse transfer capacitance		C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	20	_	pF	
Output capacitance		Coss		/	220	\rightarrow		
Switching time	Rise time	t _r	V _{GS} 10 V	-(8	> _	_	
	Turn-on time	t _{on}	VGS 0 V C C C C VOUT		17	_		
	Fall time	t _f	V _{DD} ≈ 125 V	(\mathcal{D})	13	_	ns -	
	Turn-off time	t _{off}	Duty ≦ 1%, t _W = 10 μs) —	70	_		
Total gate charge (gate-source plus		Qg		_	10			
Gate-source char		Qgs	$V_{DD} \simeq 200 \text{ V}, V_{GS} = 10 \text{ V},$		7.6		0	
Gate-drain ("Mille	r") charge	Qgd	I _D = 4 A	_	2.4	_	nC	
Gate switch charg	ge (in)	Q _{SW}			3.7			

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic	Symbol Test Condition		Тур.	Max	Unit
Drain reverse current Pulse (Note 1)	I _{DRP} —	_	_	8	Α
Forward voltage (diode)	V_{DSF} $I_{DR} = 4 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-2.0	V



4

V_{GS} = 0 V

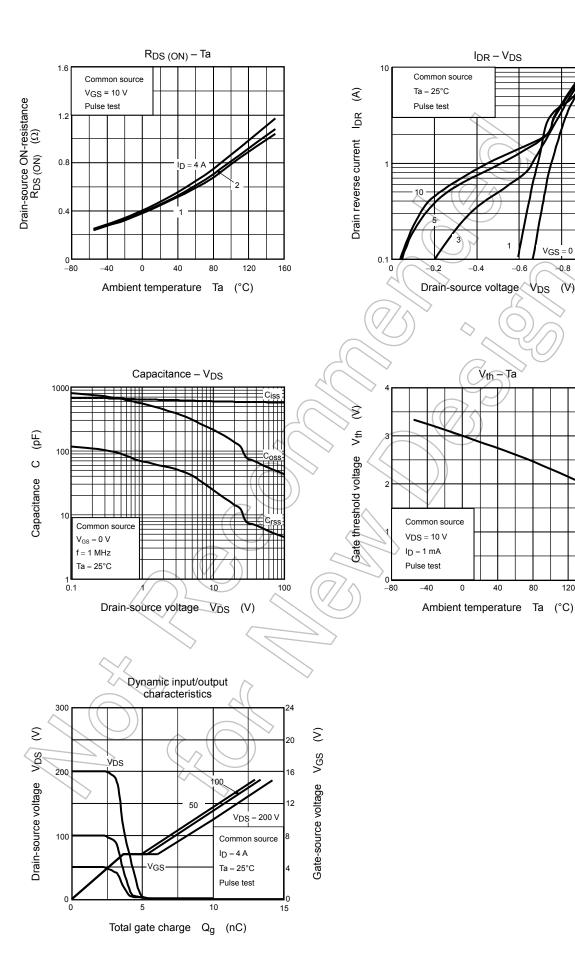
0.8

(A)

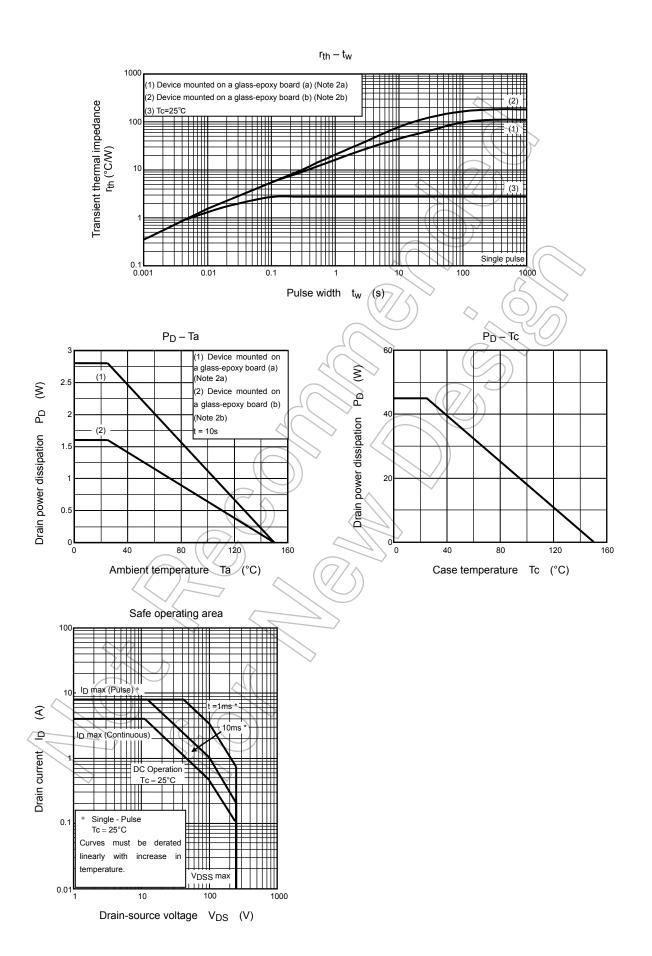
120

160

-1.0



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